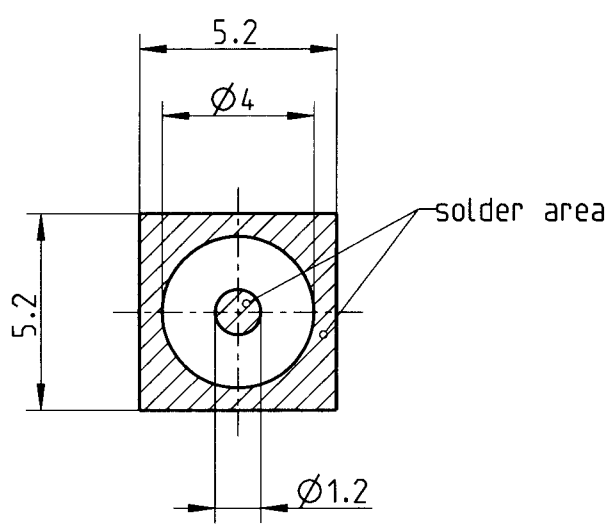


All rights strictly reserved. Reproduction or issue to third parties in any form whatever is not permitted without written authority from the proprietor. Property of Rosenberger Hochfrequenztechnik.

Leiterplatten-Layout  
PCB layout  
B 126



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formzahl: TCG\_08\_05\_05\_A4 Einzelteil  
Datei: A4\_LEITFLETTLEB.FPM  
Version: 1.0

fuer diese technische Unterlage behalten wir uns alle Rechte vor (DIN 34)

-METRIC-

ISO-Projektion  
Methode E

<b>Rosenberger</b> Hochfrequenztechnik 84526 Tittmoning    Pro/ENGINEER		general tolerance <b>ISO 2768</b> <b>RN 006-01</b>		scale:    5:1	weight(g): surface(mm <sup>2</sup> ):
		m-H    dimensions <0,5 and symmetry		material:	
		date    name	<b>Leiterplatten-Layout</b> <b>PCB layout</b>		
		drawn    14.11.2005    A_Nobis			
		check.    30.11.05 <i>WZ</i>			
		appr.    2/12/05 <i>WZ</i>			
		dimensioning incl. finish		title:	
				part-no.:	
				<b>MB_126</b>	
				sheet: 1	
				of: 1	
<b>a00</b>	<b>05-0615</b>	<b>A_Nobis</b>	<b>15.11.2005</b>	distribution to:    FE    AZ    QSM    RMT    .	
rev.change-no:		name		date	
				remarks: .	